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LOC J DIST -

REVISIONS						
P	LTR	DESCRIPTION	ECN	DATE	DWN	APVD
0		RELEASED FJ00-1227-02		10MAY2002	D.M	S.M
A		ADD P/N(-3) FJ00-1716-02		22AUG2002	D.M	S.M
B		REVISED FJD0-0125-03		30JAN04	K.R	K.S

1.6 TYP 3.5 TYP 3.3 TYP

-4: AS SHOWN

1. MATERIAL: HOUSING GLASS FILED THERMOPLASTIC, 94V-0, BLACK CONTACT COPPER ALLOY.
 2. FINISH: UNDER PLATE Ni 1.27μm min. CONTACT AREA Au 0.2μm min. P.C. BOARD ATTACHMENT AREA Tin 2μm min.

1. 材料: ハウジング ガラス入り熱可塑性ポリエステル樹脂, 94V-0、黒
 コンタクト 銅合金
 2. メッキ: コンタクト 全面Ni下地 1.27μm MIN
 接点部 0.2μm MIN金メッキ
 基板取付部 2μm MIN 錫メッキ

5.2 TYP 3.1 TYP 6.75 8.9 TYP 15.8 2X3=6 1

1 2 8 2X3=6

推奨基板寸法 (t=1.6±0.2)
 RECOMMENDED PC BOARD PATTERN

6.5±0.05X3=19.5±0.05 25.9 HSG DIM 6.5±0.05 TYP 6.75 HSG DIM 2±0.05 15.8 HSG DIM 1±0.05 2±0.05X3=6±0.05 6.5±0.05 Ø1.6 (ROUND DIA) Ø1+0.05/-0.10 (HOLE DIA) スケール 2:1

3.25 6.5 TYP 6.5X3=19.5 25.9 13 A

THIS DRAWING IS A CONTROLLED DOCUMENT FOR TYCO ELECTRONICS CORPORATION IT IS SUBJECT TO CHANGE AND THE CONTROLLING ENGINEERING ORGANIZATION SHOULD BE CONTACTED FOR THE LATEST REVISION.		DWN D. MITSUGI 10MAY2002	tyco Electronics Tyco Electronics AMP K.K. Kawasaki, Japan	
DIMENSIONS: 単位: 概 mm		CHK S. MANABE 10MAY2002	NAME 名称 HDR-ASSY-4ROW FOR E-CON. - RITS CONN. -	
TOLERANCES UNLESS OTHERWISE SPECIFIED:		APVD S. MANABE 10MAY2002	DRAWING NO 番号 C=1473567	
0 PLC ±- ±0.2		PRODUCT SPEC 製品規格 108-5765	SIZE A3	CAGE CODE 00779
1 PLC ±- ±0.2		APPLICATION SPEC 取付適用規格 -	SCALE 尺度 3:1	SHEET 1 OF 2
2 PLC ±- ±3°		WEIGHT -	RESTRICTED TO -	
3 PLC ±- ±3°		CUSTOMER DRAWING		
4 PLC ±- ±		REV B		
ANGLES ±- ±				
FINISH 仕上 -				

AMP 1470-19 REV 31MAR2000

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J

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P

LTR

DESCRIPTION

DATE

DWN

APVD

SEE SHEET 1 OF 2

- 3 : AS SHOWN

0.3 TYP
3.5 TYP
3.3 TYP

5.2 TYP
3.1 TYP
5.75
6.9 TYP
13.8

1.6 TYP
2
2
6
2X4=8
SOLDER PEG

4.4 TYP

6.5 TYP
3.25
6.5X3=19.5

25.9
13
6.5 TYP
3.25
6.5X3=19.5

推奨基板寸法 (t=1.6±0.2)

RECOMMENDED PC BOARD PATTERN

25.9 HSG DIM
6.5±0.05X3=19.5±0.05
6.5±0.05
6.5±0.05
14±0.05
13.8 HSG DIM
2±0.05X4=8±0.05
Ø1.6 (ROUND DIA)

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DWN D. MITSUGI 20AUG2002

CHK S. MITSUGI 22AUG2002

APVD S. MANABE 22AUG2002

PRODUCT SPEC

108-5765

APPLICATION SPEC

WEIGHT -

CUSTOMER DRAWING

Tyco Electronics AMP K.K.
Kawasaki, Japan

NAME

HDR-ASSY-4ROW
FOR E-CON.
- RITS CONN. -

SIZE

CAGE CODE

DRAWING NO

RESTRICTED TO

A3

00779

C=1473567

SCALE 3:1

SHEET 2 OF 2

REV B

AMP 1470-19 REV 31MAR2000